

High Voltage Latch-Up Proof, Dual SPST Switches

Data Sheet

ADG5421/ADG5423

FEATURES

Latch-up immune under all circumstances Human body model (HBM) ESD rating: 8 kV Low on resistance: 13.5 Ω ± 9 V to ± 22 V dual-supply operation 9 V to 40 V single-supply operation 48 V supply maximum ratings Fully specified at ± 15 V, ± 20 V, ± 12 V, and ± 36 V V_{DD} to V_{SS} analog signal range

APPLICATIONS

High voltage signal routing Automatic test equipment Analog front-end circuits Precision data acquisition Industrial instrumentation Amplifier gain select Relay replacement

FUNCTIONAL BLOCK DIAGRAMS

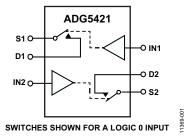


Figure 1. ADG5421

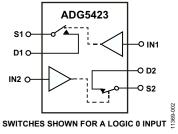


Figure 2. ADG5423

GENERAL DESCRIPTION

The ADG5421/ADG5423 are monolithic industrial, complementary metal oxide semiconductor (CMOS) analog switches containing two independent latch-up immune single-pole/single-throw (SPST) switches. Each switch conducts equally well in both directions when on, and has an input signal range that extends to the power supplies. In the off condition, signal levels up to the supplies are blocked. Both ADG5421 switches are turned on with a Logic 1 input, whereas the ADG5423 has one switch turned on and one switch turned off for a Logic 1 input. The ADG5423 exhibits break-before-make action for use in multiplexer applications.

The ultralow on resistance and on-resistance flatness of these switches make them ideal solutions for data acquisition and gain switching applications where low distortion is critical. The latch-up immune construction and high ESD rating make these switches more robust in harsh environments.

PRODUCT HIGHLIGHTS

- Trench isolation guards against latch-up. A dielectric trench separates the P channel and N channel transistors, thereby preventing latch-up even under severe overvoltage conditions.
- Low Ron of 13.5 Ω.
- 3. Dual-supply operation. For applications where the analog signal is bipolar, the ADG5421/ADG5423 can operate from dual supplies up to ± 22 V.
- 4. Single-supply operation. For applications where the analog signal is unipolar, the ADG5421/ADG5423 can operate from a single-rail power supply up to 40 V.
- 5. 3 V logic compatible digital inputs: $V_{INH} = 2.0 \text{ V}$, $V_{INL} = 0.8 \text{ V}$.
- 6. No V_L logic power supply required.
- 7. Available in 10-lead MSOP package.

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REVISION HISTORY

9/13—Revision 0: Initial Version

SPECIFICATIONS

±15 V DUAL SUPPLY

 V_{DD} = +15 V \pm 10%, V_{SS} = -15 V \pm 10%, GND = 0 V, unless otherwise noted.

Table 1.

Parameter	25°C	-40°C to +85°C	-40°C to +125°C	Unit	Test Conditions/Comments
ANALOG SWITCH					
Analog Signal Range			V_{DD} to V_{SS}	V	
On Resistance, R _{ON}	13.5			Ωtyp	$V_S = \pm 10 \text{ V}, I_S = -10 \text{ mA}$; see Figure 24
	15	19	23	Ω max	$V_{DD} = +13.5 \text{ V}, V_{SS} = -13.5 \text{ V}$
On-Resistance Match Between Channels, ΔR_{ON}	0.1			Ωtyp	$V_S = \pm 10 \text{ V}, I_S = -10 \text{ mA}$
	0.8	1.3	1.4	Ω max	
On-Resistance Flatness, R _{FLAT (ON)}	1.8			Ωtyp	$V_S = \pm 10 \text{ V, } I_S = -10 \text{ mA}$
	2.2	2.7	3.1	Ω max	
LEAKAGE CURRENTS					$V_{DD} = +16.5 \text{ V}, V_{SS} = -16.5 \text{ V}$
Source Off Leakage, Is (Off)	±0.05			nA typ	$V_S = \pm 10 \text{ V}, V_D = \mp 10 \text{ V}$; see Figure 23
	±0.25	±1	±10	nA max	
Drain Off Leakage, I _D (Off)	±0.05			nA typ	$V_S = \pm 10 \text{ V}, V_D = \mp 10 \text{ V}$; see Figure 23
3,,,,,	±0.25	±1	±10	nA max	15 = 16 1, 16 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1
Channel On Leakage, I _D (On), I _S (On)	±0.1			nA typ	$V_S = V_D = \pm 10 \text{ V}$; see Figure 22
Charmer Off Leakage, ID (Off), IS (Off)	±0.1	±4	±20	nA max	v5 = vb = ±10 v, see rigure 22
DIGITAL INPUTS					
Input High Voltage, V _{INH}			2.0	V min	
Input Low Voltage, V _{INL}			0.8	V max	
Input Current, I _{INL} or I _{INH}	0.002			μA typ	$V_{IN} = V_{GND}$ or V_{DD}
			±0.1	μA max	
Digital Input Capacitance, C _{IN}	6			pF typ	
DYNAMIC CHARACTERISTICS ¹					
ton	185			ns typ	$R_L = 300 \Omega, C_L = 35 pF$
	220	273	313	ns max	V _s = 10 V; see Figure 29
t _{OFF}	163			ns typ	$R_L = 300 \Omega, C_L = 35 pF$
	196	219	242	ns max	V _s = 10 V; see Figure 29
Break-Before-Make Time Delay, t _D (ADG5423 Only)	73			ns typ	$R_L = 300 \Omega, C_L = 35 pF$
			21	ns min	$V_{S1} = V_{S2} = 10 \text{ V}$; see Figure 31
Charge Injection, Q _{INJ}	95			pC typ	$V_S = 0 \text{ V}, R_S = 0 \Omega, C_L = 1 \text{ nF; see}$ Figure 30
Off Isolation	-55			dB typ	$R_L = 50 \Omega$, $C_L = 5 pF$, $f = 1 MHz$; see Figure 25
Channel-to-Channel Crosstalk	-85			dB typ	$R_L = 50 \Omega$, $C_L = 5 pF$, $f = 1 MHz$; see Figure 28
Total Harmonic Distortion + Noise	0.01			% typ	$R_L = 1 kΩ$, 15 V p-p, $f = 20 Hz$ to 20 kHz; see Figure 26
−3 dB Bandwidth	250			MHz typ	$R_L = 50 \Omega$, $C_L = 5 pF$; see Figure 27
Insertion Loss	-1			dB typ	$R_L = 50 \Omega$, $C_L = 5 pF$, $f = 1 MHz$; see Figure 27
C _s (Off)	12			pF typ	$V_S = 0 \text{ V, } f = 1 \text{ MHz}$
C _D (Off)	13			pF typ	$V_S = 0 V, f = 1 MHz$
C_D (On), C_S (On)	44			pF typ	$V_S = 0 V, f = 1 MHz$
POWER REQUIREMENTS					$V_{DD} = +16.5 \text{ V}, V_{SS} = -16.5 \text{ V}$
I _{DD}	45			μA typ	Digital inputs = 0 V or V _{DD}
	55		70	μA max	_ ,
I _{SS}	0.001			μA typ	Digital inputs = 0 V or V _{DD}
			1	μA max	_ ,
V_{DD}/V_{SS}			±9/±22	V min/V max	GND = 0 V

 $^{^{\}mbox{\tiny 1}}$ Guaranteed by design; not subject to production test.

±20 V DUAL SUPPLY

 V_{DD} = +20 V \pm 10%, V_{SS} = -20 V \pm 10%, GND = 0 V, unless otherwise noted.

Table 2.

Parameter	25°C	-40°C to +85°C	-40°C to +125°C	Unit	Test Conditions/Comments
ANALOG SWITCH					
Analog Signal Range			V _{DD} to V _{SS}	V	
On Resistance, R _{ON}	12.5			Ωtyp	$V_S = \pm 15 \text{ V}, I_S = -10 \text{ mA}; \text{ see Figure 24}$
	14	18	22	Ω max	$V_{DD} = +18 \text{ V}, V_{SS} = -18 \text{ V}$
On-Resistance Match Between Channels, ΔR _{ON}	0.1			Ωtyp	$V_S = \pm 15 \text{ V}, I_S = -10 \text{ mA}$
	0.8	1.3	1.4	Ω max	
On-Resistance Flatness, R _{FLAT (ON)}	2.3			Ωtyp	$V_S = \pm 15 \text{ V}, I_S = -10 \text{ mA}$
	2.7	3.3	3.7	Ω max	
LEAKAGE CURRENTS					$V_{DD} = +22 \text{ V}, V_{SS} = -22 \text{ V}$
Source Off Leakage, Is (Off)	±0.05			nA typ	$V_S = \pm 15 \text{ V}, V_D = \mp 15 \text{ V}; \text{ see Figure 23}$
	±0.25	±1	±10	nA max	
Drain Off Leakage, I _D (Off)	±0.05			nA typ	$V_S = \pm 15 \text{ V}, V_D = \mp 15 \text{ V}; \text{ see Figure 23}$
	±0.25	±1	±10	nA max	
Channel On Leakage, ID (On), IS (On)	±0.1			nA typ	$V_S = V_D = \pm 15 \text{ V}$; see Figure 22
	±0.4	±4	±20	nA max	,
DIGITAL INPUTS					
Input High Voltage, V _{INH}			2.0	V min	
Input Low Voltage, V _{INL}			0.8	V max	
Input Current, I _{INL} or I _{INH}	0.002			μA typ	$V_{IN} = V_{GND}$ or V_{DD}
			±0.1	μA max	
Digital Input Capacitance, C _{IN}	6			pF typ	
DYNAMIC CHARACTERISTICS ¹					
ton	168			ns typ	$R_L = 300 \Omega$, $C_L = 35 pF$, $V_S = 10 V$; see
					Figure 29
	199	243	276	ns max	$V_S = 10 \text{ V}$; see Figure 29
toff	156			ns typ	$R_L = 300 \Omega, C_L = 35 pF$
	184	204	218	ns max	$V_S = 10 \text{ V}$; see Figure 29
Break-Before-Make Time Delay, t _D (ADG5423 Only)	65			ns typ	$R_L = 300 \Omega, C_L = 35 pF$
			38	ns min	$V_{S1} = V_{S2} = 10 \text{ V}$; see Figure 31
Charge Injection, Q _{INJ}	120			pC typ	$V_S = 0$ V, $R_S = 0$ Ω , $C_L = 1$ nF; see Figure 30
Off Isolation	-55			dB typ	$R_L = 50 \Omega$, $C_L = 5 pF$, $f = 1 MHz$; see Figure 25
Channel-to-Channel Crosstalk	-85			dB typ	$R_L = 50 \Omega$, $C_L = 5 pF$, $f = 1 MHz$; see Figure 28
Total Harmonic Distortion + Noise	0.01			% typ	$R_L = 1 \text{ k}\Omega$, 20 V p-p, f = 20 Hz to 20 kHz; see Figure 26
–3 dB Bandwidth	250			MHz typ	$R_L = 50 \Omega$, $C_L = 5 pF$; see Figure 27
Insertion Loss	-0.8			dB typ	$R_L = 50 \Omega$, $C_L = 5 pF$, $f = 1 MHz$; see Figure 27
C _s (Off)	11			pF typ	$V_S = 0 \text{ V, } f = 1 \text{ MHz}$
C _D (Off)	12			pF typ	$V_S = 0 V, f = 1 MHz$
C_D (On), C_S (On)	44			pF typ	$V_S = 0 V, f = 1 MHz$
POWER REQUIREMENTS					$V_{DD} = +22 \text{ V}, V_{SS} = -22 \text{ V}$
I _{DD}	50			μA typ	Digital inputs = 0 V or V _{DD}
	70		110	μA max	
lss	0.001		1	μΑ typ μΑ max	Digital inputs = 0 V or V _{DD}
		1	1.	μαλ	

¹ Guaranteed by design; not subject to production test.

12 V SINGLE SUPPLY

 V_{DD} = 12 V \pm 10%, V_{SS} = 0 V, GND = 0 V, unless otherwise noted.

Table 3.

Parameter	25°C	-40°C to +85°C	-40°C to +125°C	Unit	Test Conditions/Comments
ANALOG SWITCH					
Analog Signal Range			0 V to V _{DD}	V	
On Resistance, R _{ON}	26			Ωtyp	$V_S = 0 \text{ V to } 10 \text{ V, } I_S = -10 \text{ mA; see}$ Figure 24
	30	38	44	Ω max	$V_{DD} = 10.8 \text{ V}, V_{SS} = 0 \text{ V}$
On-Resistance Match Between Channels, ΔR_{ON}	0.1			Ωtyp	$V_s = 0 \text{ V to } 10 \text{ V, } I_s = -10 \text{ mA}$
	1	1.5	1.6	Ω max	
On-Resistance Flatness, R _{FLAT (ON)}	5.5			Ωtyp	$V_S = 0 \text{ V to } 10 \text{ V}, I_S = -10 \text{ mA}$
	6.8	8.3	12.3	Ω max	
LEAKAGE CURRENTS					$V_{DD} = +13.2 \text{ V}, V_{SS} = 0 \text{ V}$
Source Off Leakage, I₅ (Off)	±0.05			nA typ	$V_S = 1 \text{ V to } 10 \text{ V}, V_D = 10 \text{ V to } 1 \text{ V}; \text{ see}$ Figure 23
	±0.25	±1	±10	nA max	
Drain Off Leakage, I _D (Off)	±0.05			nA typ	$V_S = 1 \text{ V to } 10 \text{ V}, V_D = 10 \text{ V to } 1 \text{ V}; \text{ see}$ Figure 23
	±0.25	±1	±10	nA max	
Channel On Leakage, I_D (On), I_S (On)	±0.1			nA typ	$V_S = V_D = 1 \text{ V to } 10 \text{ V}$; see Figure 22
	±0.4	±4	±20	nA max	
DIGITAL INPUTS					
Input High Voltage, V _{INH}			2.0	V min	
Input Low Voltage, V _{INL}			0.8	V max	
Input Current, I _{INL} or I _{INH}	0.002			μA typ	$V_{IN} = V_{GND} \text{ or } V_{DD}$
			±0.1	μA max	
Digital Input Capacitance, C _{IN}	6			pF typ	
DYNAMIC CHARACTERISTICS ¹					
ton	295			ns typ	$R_L = 300 \Omega, C_L = 35 pF$
	370	470	540	ns max	$V_s = 8 \text{ V}$; see Figure 29
toff	192			ns typ	$R_L = 300 \Omega, C_L = 35 pF$
	235	273	295	ns max	$V_s = 8 V$; see Figure 29
Break-Before-Make Time Delay, t _D (ADG5423 Only)	142			ns typ	$R_L = 300 \Omega, C_L = 35 pF$
			78	ns min	$V_{S1} = V_{S2} = 8 \text{ V}$; see Figure 31
Charge Injection, Q _{INJ}	55			pC typ	$V_S = 6 \text{ V}, R_S = 0 \Omega, C_L = 1 \text{ nF; see}$ Figure 30
Off Isolation	−55			dB typ	R_L = 50 Ω , C_L = 5 pF, f = 1 MHz; see Figure 25
Channel-to-Channel Crosstalk	-85			dB typ	$R_L = 50 \Omega$, $C_L = 5 pF$, $f = 1 MHz$; see Figure 28
Total Harmonic Distortion + Noise	0.03			% typ	$R_L = 1 \text{ k}\Omega$, 6 V p-p, f = 20 Hz to 20 kHz; see Figure 26
–3 dB Bandwidth	290			MHz typ	$R_L = 50 \Omega$, $C_L = 5 pF$; see Figure 27
Insertion Loss	-1.7			dB typ	$R_L = 50 \Omega$, $C_L = 5 pF$, $f = 1 MHz$; see Figure 27
C _s (Off)	14			pF typ	$V_s = 6 V, f = 1 MHz$
C _D (Off)	15			pF typ	$V_s = 6 V, f = 1 MHz$
C_D (On), C_S (On)	38			pF typ	$V_s = 6 V, f = 1 MHz$
POWER REQUIREMENTS					V _{DD} = 13.2 V
I _{DD}	40			μA typ	Digital inputs = 0 V or V_{DD}
	50		65	μA max	
V_{DD}			9/40	V min/V max	$GND = 0 V, V_{SS} = 0 V$

 $^{^{\}mbox{\tiny 1}}$ Guaranteed by design; not subject to production test.

36 V SINGLE SUPPLY

 V_{DD} = 36 V \pm 10%, V_{SS} = 0 V, GND = 0 V, unless otherwise noted.

Table 4.

Parameter	25°C	-40°C to +85°C	-40°C to +125°C	Unit	Test Conditions/Comments
ANALOG SWITCH					
Analog Signal Range			0 V to V _{DD}	V	
On Resistance, R _{ON}	14.5			Ωtyp	$V_s = 0 \text{ V to } 30 \text{ V}, I_s = -10 \text{ mA}; \text{ see Figure } 24$
·	16	20	24	Ω max	$V_{DD} = 32.4 \text{ V}, V_{SS} = 0 \text{ V}$
On-Resistance Match Between Channels, ΔR_{ON}	0.1			Ωtyp	$V_S = 0 \text{ V to } 30 \text{ V, } I_S = -10 \text{ mA}$
	0.8	1.3	1.4	Ω max	
On-Resistance Flatness, R _{FLAT (ON)}	3.5			Ωtyp	$V_s = 0 \text{ V to } 30 \text{ V, } I_s = -10 \text{ mA}$
	4.3	5.5	6.5	Ω max	
LEAKAGE CURRENTS					$V_{DD} = 39.6 \text{ V}, V_{SS} = 0 \text{ V}$
Source Off Leakage, I _s (Off)	±0.05			nA typ	$V_S = 1 \text{ V to } 30 \text{ V}, V_D = 30 \text{ V to } 1 \text{ V}; \text{ see}$ Figure 23
	±0.25	±1	±10	nA max	
Drain Off Leakage, I _D (Off)	±0.05			nA typ	$V_S = 1 \text{ V to } 30 \text{ V}, V_D = 30 \text{ V to } 1 \text{ V}; \text{ see}$ Figure 23
	±0.25	±1	±10	nA max	
Channel On Leakage, I_D (On), I_S (On)	±0.1			nA typ	$V_S = V_D = 1 \text{ V to } 30 \text{ V}$; see Figure 22
	±0.4	±4	±20	nA max	
DIGITAL INPUTS					
Input High Voltage, V _{INH}			2.0	V min	
Input Low Voltage, V _{INL}			0.8	V max	
Input Current, I _{INL} or I _{INH}	0.002			μA typ	$V_{IN} = V_{GND}$ or V_{DD}
•			±0.1	μA max	
Digital Input Capacitance, C _{IN}	6			pF typ	
DYNAMIC CHARACTERISTICS ¹					
t _{on}	181			ns typ	$R_L = 300 \Omega$, $C_L = 35 pF$
	210	245	280	ns max	V _s = 18 V; see Figure 29
t _{OFF}	170			ns typ	$R_L = 300 \Omega, C_L = 35 pF$
	192	205	220	ns max	V _s = 18 V; see Figure 29
Break-Before-Make Time Delay, t _D (ADG5423 Only)	66			ns typ	$R_L = 300 \Omega, C_L = 35 pF$
			37	ns min	$V_{S1} = V_{S2} = 18 \text{ V}$; see Figure 31
Charge Injection, Q _{INJ}	110			pC typ	$V_S = 18 \text{ V}, R_S = 0 \Omega, C_L = 1 \text{ nF}; \text{ see Figure 30}$
Off Isolation	-55			dB typ	$R_L = 50 \Omega$, $C_L = 5 pF$, $f = 1 MHz$; see Figure 25
Channel-to-Channel Crosstalk	-85			dB typ	$R_L = 50 \Omega$, $C_L = 5 pF$, $f = 1 MHz$; see Figure 28
Total Harmonic Distortion + Noise	0.01			% typ	$R_L = 1 \text{ k}\Omega$, 18 V p-p, f = 20 Hz to 20 kHz; see Figure 26
–3 dB Bandwidth	260			MHz typ	$R_L = 50 \Omega$, $C_L = 5 pF$; see Figure 27
Insertion Loss	-0.9			dB typ	$R_L = 50 \Omega$, $C_L = 5 pF$, $f = 1 MHz$; see Figure 27
Cs (Off)	13			pF typ	$V_S = 18 \text{ V, f} = 1 \text{ MHz}$
C _D (Off)	16			pF typ	$V_s = 18 \text{ V, f} = 1 \text{ MHz}$
C_D (On), C_S (On)	38			pF typ	$V_S = 18 \text{ V, f} = 1 \text{ MHz}$
POWER REQUIREMENTS					$V_{DD} = 39.6 \text{ V}$
I _{DD}	80			μA typ	Digital inputs = 0 V or V _{DD}
	100		130	μA max	
V_{DD}			9/40	V min/V max	$GND = 0 V, V_{SS} = 0 V$

¹ Guaranteed by design; not subject to production test.

CONTINUOUS CURRENT PER CHANNEL, Sx OR Dx

Table 5.

Parameter	25°C	85°C	125°C	Unit	Test Conditions/Comments
CONTINUOUS CURRENT, Sx OR Dx					MSOP ($\theta_{JA} = 133.1^{\circ}$ C/W)
$V_{DD} = +15 \text{ V}, V_{SS} = -15 \text{ V}$	84	58	39	mA maximum	
$V_{DD} = +20 \text{ V}, V_{SS} = -20 \text{ V}$	89	60	41	mA maximum	
$V_{DD} = 12 \text{ V}, V_{SS} = 0 \text{ V}$	67	47	32	mA maximum	
$V_{DD}=36V,V_{SS}=0V$	87	59	40	mA maximum	

ABSOLUTE MAXIMUM RATINGS

 $T_A = 25$ °C, unless otherwise noted.

Table 6.

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Parameter	Rating
V _{DD} to V _{SS}	48 V
V _{DD} to GND	−0.3 V to +48 V
V _{SS} to GND	+0.3 V to -48 V
Analog Inputs ¹	$V_{SS} - 0.3 \text{ V to } V_{DD} + 0.3 \text{ V or}$ 30 mA, whichever occurs first
Digital Inputs ¹	V_{SS} – 0.3 V to V_{DD} + 0.3 V or 30 mA, whichever occurs first
Peak Current, Sx or Dx Pins	300 mA (pulsed at 1 ms, 10% duty cycle maximum)
Continuous Current, Sx or Dx ²	Data + 15%
Temperature Range	
Operating	−40°C to +125°C
Storage	−65°C to +150°C
Junction Temperature	150°C
Thermal Impedance, θ_{JA}	
10-Lead MSOP (4-Layer Board)	133.1°C/W
Reflow Soldering Peak Temperature, Pb Free	As per JEDEC J-STD-020
Human Body Model (HBM) ESD	8 kV

¹ Overvoltages at the INx, Sx, and Dx pins are clamped by internal diodes. Limit current to the maximum ratings given.

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Only one absolute maximum rating can be applied at any one time.

ESD CAUTION



ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

² See Table 5.

PIN CONFIGURATION AND FUNCTION DESCRIPTIONS

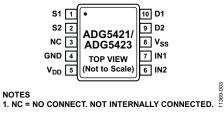


Figure 3. Pin Configuration

Table 7. Pin Function Descriptions

Pin No.	Mnemonic	Description	
1	S1	Source Terminal 1. This pin can be an input or output.	
2	S2	Source Terminal 2. This pin can be an input or output.	
3	NC	No Connect. Not internally connected.	
4	GND	Ground (0 V) Reference.	
5	V_{DD}	Most Positive Power Supply Potential.	
6	IN2	Logic Control Input.	
7	IN1	Logic Control Input.	
8	V _{SS}	Most Negative Power Supply Potential.	
9	D2	Drain Terminal 2. This pin can be an input or output.	
10	D1	Drain Terminal 1. This pin can be an input or output.	

Table 8. ADG5421 Truth Table

INx	Switch Conditions
0	Off
1	On

Table 9. ADG5423 Truth Table

_						
II	٧x	Switch 1 Condition	Switch 2 Condition			
0		Off	On			
1		On	Off			

TYPICAL PERFORMANCE CHARACTERISTICS

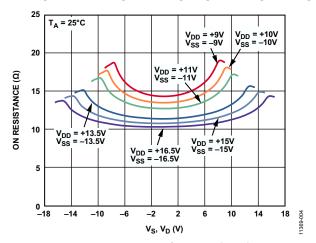


Figure 4. On Resistance as a Function of V_S , V_D (Dual Supply: $\pm 10 \text{ V}$, $\pm 15 \text{ V}$)

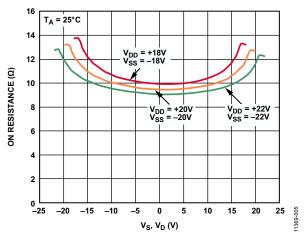


Figure 5. On Resistance as a Function of V_S , V_D (Dual Supply: $\pm 20 \text{ V}$)

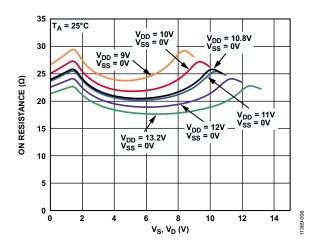


Figure 6. On Resistance as a Function of V_S , V_D (Single Supply: 10 V, 12 V)

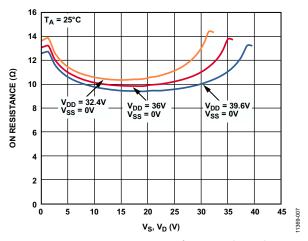


Figure 7. On Resistance as a Function of V_S , V_D (Single Supply: 36 V)

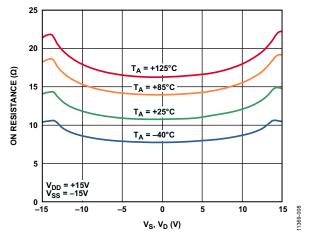


Figure 8. On Resistance as a Function of V_S (V_D) for Different Temperatures, ± 15 V Dual Supply

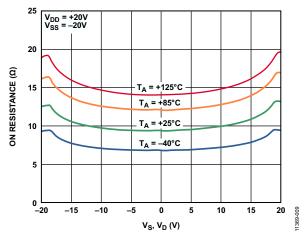


Figure 9. On Resistance as a Function of $V_S(V_D)$ for Different Temperatures, ± 20 V Dual Supply

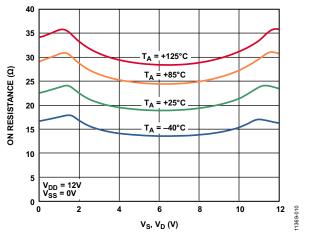


Figure 10. On Resistance as a Function of V_S (V_D) for Different Temperatures, 12 V Single Supply

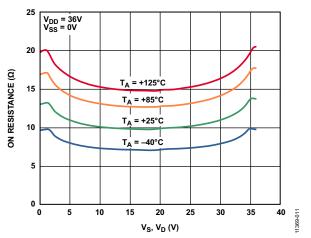


Figure 11. On Resistance as a Function of V_S (V_D) for Different Temperatures, 36 V Single Supply

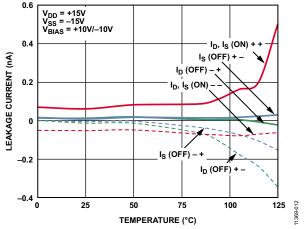


Figure 12. Leakage Currents as a Function of Temperature, ±15 V Dual Supply

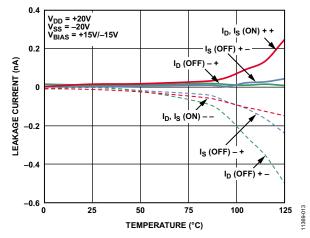


Figure 13. Leakage Currents as a Function of Temperature, ±20 V Dual Supply

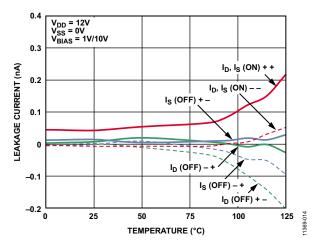


Figure 14. Leakage Currents as a Function of Temperature, 12 V Single Supply

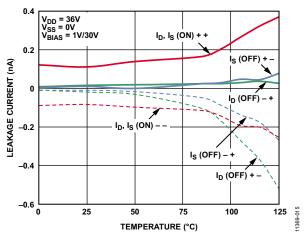


Figure 15. Leakage Currents as a Function of Temperature, 36 V Single Supply

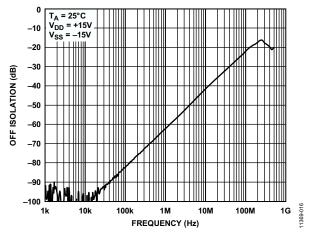


Figure 16. Off Isolation vs. Frequency

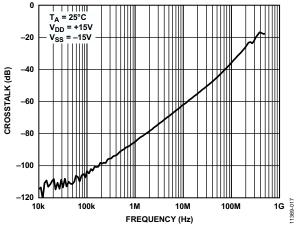


Figure 17. Crosstalk vs. Frequency

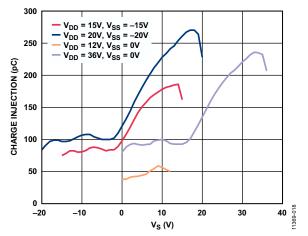


Figure 18. Charge Injection vs. Source Voltage (Vs)

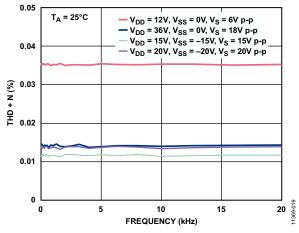


Figure 19. THD + N vs. Frequency

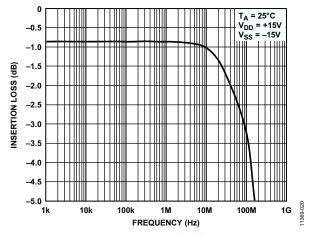


Figure 20. Bandwidth

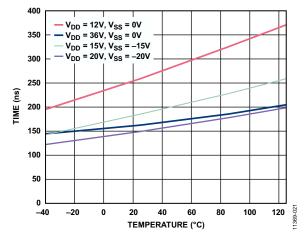


Figure 21. t_{TRANSITION} Times vs. Temperature

TEST CIRCUITS

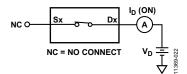


Figure 22. On Leakage

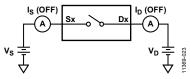
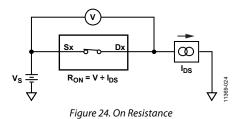


Figure 23. Off Leakage



OFF ISOLATION = 20 log Vout Vss

Figure 25. Off Isolation

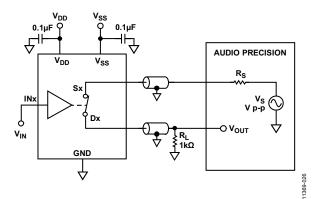


Figure 26. THD + Noise

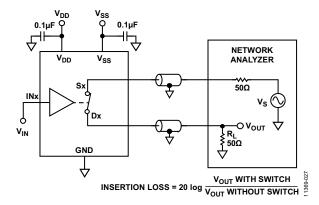


Figure 27. Bandwidth

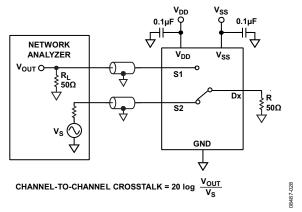


Figure 28. Channel-to-Channel Crosstalk

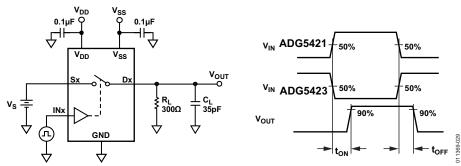


Figure 29. Switching Times, ton and toff

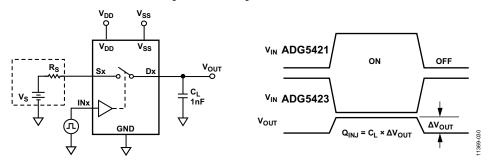


Figure 30. Charge Injection

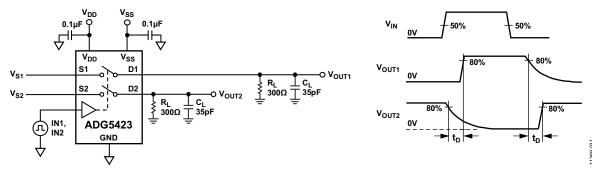


Figure 31. Break-Before-Make Time Delay

TERMINOLOGY

I_{DD}

IDD represents the positive supply current.

Tee

Iss represents the negative supply current.

V_D, V_S

 V_D and V_S represent the analog voltage on Terminal D and Terminal S, respectively.

Ron

 R_{ON} is the ohmic resistance between Terminal D and Terminal S.

ΔR_{ON}

 $\Delta R_{\rm ON}$ represents the difference between the $R_{\rm ON}$ of any two channels.

R_{FLAT} (ON)

 $R_{\rm FLAT\,(ON)}$ represents the difference between the maximum and minimum value of on resistance as measured over the specified analog signal range.

Is (Off)

I_S (Off) is the source leakage current with the switch off.

In (Off)

I_D (Off) is the drain leakage current with the switch off.

I_D (On), I_S (On)

 $I_{D}\left(On\right)$ and $I_{S}\left(On\right)$ represent the channel leakage currents with the switch on.

V_{INL}

 V_{INL} is the maximum input voltage for Logic 0.

V_{INH}

 V_{INH} is the minimum input voltage for Logic 1.

IINL, IINH

 I_{INL} and I_{INH} represent the low and high input currents of the digital inputs.

C_D (Off)

 C_D (Off) represents the off switch drain capacitance, which is measured with reference to ground.

Cs (Off)

C_S (Off) represents the off switch source capacitance, which is measured with reference to ground.

C_D (On), C_S (On)

 C_D (On) and C_S (On) represent on switch capacitances, which are measured with reference to ground.

C_{IN}

C_{IN} represents digital input capacitance.

ton

 $t_{\rm ON}$ represents the delay time between the 50% and 90% points of the digital input and switch on condition.

toff

t_{OFF} represents the delay time between the 50% and 90% points of the digital input and switch off condition.

tο

 t_{D} represents the off time measured between the 80% point of both switches when switching from one address state to another.

Off Isolation

Off isolation is a measure of unwanted signal coupling through an off channel.

Charge Injection

Charge injection is a measure of the glitch impulse transferred from the digital input to the analog output during switching.

Crosstalk

Crosstalk is a measure of unwanted signal that is coupled through from one channel to another as a result of parasitic capacitance.

Bandwidth

Bandwidth is the frequency at which the output is attenuated by 3 dB from its dc level.

Total Harmonic Distortion + Noise (THD + N)

The ratio of the harmonic amplitude plus noise of the signal to the fundamental is represented by THD + N.

APPLICATIONS INFORMATION

The ADG54xx family of switches and multiplexers provide a robust solution for instrumentation, industrial, aerospace, and other harsh environments that are prone to latch-up, which is an undesirable high current state that can lead to device failure and persists until the power supply is turned off. The ADG5421/ADG5423 high voltage switches allow single-supply operation from 9 V to 40 V and dual-supply operation from ± 9 V to ± 22 V. The ADG5421/ADG5423 (as well as other select devices within this family) achieve an 8 kV human body model ESD rating, which provides a robust solution, eliminating the need for separate protection circuitry designs in some applications.

TRENCH ISOLATION

In the ADG5421/ADG5423, an insulating oxide layer (trench) is placed between the NMOS and the PMOS transistors of each CMOS switch. Parasitic junctions, which occur between the transistors in junction-isolated switches, are eliminated, and the result is a completely latch-up immune switch.

In junction isolation, the N and P wells of the PMOS and NMOS transistors form a diode that is reverse-biased under normal operation. However, during overvoltage conditions, this diode can become forward-biased. The two transistors form a silicon-controlled rectifier (SCR) type circuit, causing a significant amplification of the current that, in turn, leads to latch-up. With trench isolation, this diode is removed, and the result is a latch-up immune switch.

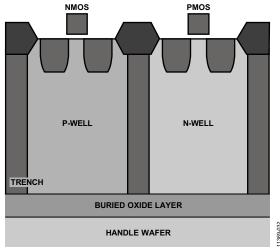


Figure 32. Trench Isolation

OUTLINE DIMENSIONS

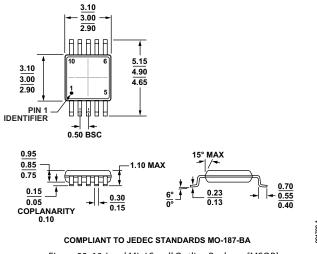


Figure 33. 10-Lead Mini Small Outline Package [MSOP] (RM-10) Dimensions shown in millimeters

ORDERING GUIDE

Model ¹	Temperature Range	Package Description	Package Option	Branding
ADG5421BRMZ	-40°C to +125°C	10-Lead Mini Small Outline Package [MSOP]	RM-10	S47
ADG5421BRMZ-RL7	−40°C to +125°C	10-Lead Mini Small Outline Package [MSOP]	RM-10	S47
ADG5423BRMZ	-40°C to +125°C	10-Lead Mini Small Outline Package [MSOP]	RM-10	S3D
ADG5423BRMZ-RL7	−40°C to +125°C	10-Lead Mini Small Outline Package [MSOP]	RM-10	S3D

¹ Z = RoHS Compliant Part.

NOTES

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